

AN 1999:199668 HCAPLUS  
 DN 130:199648  
 TI Lead-free **solder** alloy  
 IN Osaka, Takeshi; Kato, Rikiya  
 PA Senju Metal Industry Co., Ltd., Japan; Murata Mfg. Co., Ltd.  
 SO Jpn. Kokai Tokkyo Koho, 4 pp.  
 CODEN: JKXXAF

DT Patent  
 LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 11077368	A2	19990323	JP 1997-251405	19970902
PRAI	JP 1997-251405		19970902		

AB A Pb-free **solder** alloy is a **Sn** alloy contg. **Sb**  
 1-10 (esp., 1-5), **Cu** 1-4, **Bi** 1-6, and In 1-5%. The  
 alloy has a solidus temp. of .gtoreq.200.degree..